

METHOD, SYSTEM, AND APPARATUS FOR
EMBEDDING CIRCUITS

Abstract of the Invention

5 A method, system, and apparatus for embedding circuits. The present invention
allows reduction in the size of fabricated multichip modules by embedding circuitry
within a substrate. A first layer of dielectric material is provided and a circuit having a
predetermined length, width, and depth is provided. Then, a cavity is formed in the first
layer of dielectric material substantially corresponding to the predetermined length and
10 width of the circuit. After the cavity is formed, the circuit is deposited into the cavity.
Once the circuit is deposited, a second layer of dielectric material may be provided to
cover the circuit.